

Electronic Patent Application Fee Transmittal				
Application Number:	10049270			
Filing Date:	27-Jun-2002			
Title of Invention:	MULTILAYER PRINTED WIRING BOARD, SOLDER RESIST COMPOSITION, METHOD FOR MANUFACTURING MULTILAYER PRINTED WIRING BOARD, AND SEMICONDUCTOR DEVICE			
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Attorney Docket Number:	312302US40PCT			
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Basic Filing:				
Pages:				
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Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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